

**Product / Package Information**

Package	TO92
Body Size	
Lead Count	3
Terminal Finish	100Sn

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	9.78 E-02	86.0	860000	45.31		453097
Thermosets	Epoxy Resin	Proprietary	8.53 E-03	7.5	75000	3.95		39514
Thermosets	Phenol Resin	Proprietary	4.55 E-03	4.0	40000	2.11		21074
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.27 E-03	2.0	20000	1.05		10537
Other inorganic materials	Carbon Black	1333-86-3	5.69 E-04	0.5	5000	0.26		2634
Subtotal			1.14 E-01	100	1000000	52.69		526858

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.05 E-02	97.50	975000	41.90		418957
Copper & its alloys	Iron	7439-89-6	2.18 E-03	2.35	23500	1.01		10098
Copper & its alloys	Zinc	7440-66-6	1.11 E-04	0.12	1200	0.05		516
Copper & its alloys	Phosphorus	7723-14-0	2.78 E-05	0.03	300	0.01		129
Subtotal			9.28 E-02	100	1000000	42.97		429699

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	6.50 E-05	100.0	1000000	0.03		301

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	7.28 E-03	100.0	1000000	3.37		33714

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.62 E-03	99.99	1000000	0.75		7523

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.06 E-04	100.0	1000000	0.10		952

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.64 E-04	80	800000	0.08		762
Thermosets	Epoxy Resin	Proprietary	3.08 E-05	15	150000	0.01		143
Others	Curing agent & hardener	Proprietary	1.03 E-05	5	50000	0.005		48
Subtotal			2.06 E-04	100	1000000	0.10		952

<b>Package Totals</b>			<b>Weight (g)</b>			<b>Percentage (%)</b>		<b>PPM</b>
			2.16 E-01			100.00		1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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